

Material Content Data Sheet								
Sales Product Name	IM12B15CC1			**Issued**		25. March 2024		
MA#	MA006034401							
Package	PG-MDIP-24-61			**Weight:**		6187.08 mg		
Construction Element	**Material group**	Materials	**CAS if applicable**	**Weight [mg]**	**Average mass [%]**	**Sum [%]**	**Average mass [ppm]**	**Sum [ppm]**
chip_01	inorganic material	silicon	7440-21-3	6.694	0.11	0.11	1082	1082
chip_02	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	531	531
chip_03	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	531	531
chip_04	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	531	531
chip_05	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	531	531
chip_06	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	531	531
chip_07	inorganic material	silicon	7440-21-3	3.285	0.05	0.05	531	531
chip_08	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	222	222
chip_09	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	222	222
chip_10	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	222	222
chip_11	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	222	222
chip_12	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	222	222
chip_13	inorganic material	silicon	7440-21-3	1.371	0.02	0.02	222	222
leadframe	inorganic material	alumina	1344-28-1	580.445	9.38	9.38	93815	93815
wire	noble metal	gold	7440-57-5	0.756	0.01		122	
	non noble metal	aluminium	7429-90-5	36.247	0.59	0.60	5858	5980
encapsulation	organic material	carbon black	1333-86-4	30.698	0.50		4962	
	plastics	epoxy resin	-	383.722	6.20		62020	
	inorganic material	silicondioxide	60676-86-0	3422.804	55.37	62.07	553215	620197
leadfinish	non noble metal	tin	7440-31-5	41.697	0.67	0.67	6739	6739
plating	non noble metal	nickel	7440-02-0	0.914	0.01	0.01	148	148
solder	non noble metal	antimony	7440-36-0	0.585	0.01		95	
	noble metal	silver	7440-22-4	1.463	0.02		236	
	non noble metal	tin	7440-31-5	3.803	0.06	0.09	615	946
glue	plastics	acrylic resin	-	0.249			40	
	plastics	maleimide resin	-	0.249			40	
	noble metal	silver	7440-22-4	0.746	0.01		121	
	inorganic material	silicondioxide	60676-86-0	0.778	0.01		126	
	plastics	epoxy resin	-	1.167	0.02	0.04	189	516
smd	inorganic material	silicondioxide	60676-86-0	0.003			1	
	noble metal	gold	7440-57-5	0.012			2	
	noble metal	palladium	7440-05-3	0.019			3	
	organic material	ethyl cellulose	9004-57-3	0.024			4	
	noble metal	silver	7440-22-4	0.030			5	
	organic material	DEGBE	112-34-5	0.105			17	
	inorganic material	cobalt(II)oxide	1307-96-6	0.200			32	
	inorganic material	copperoxide	1317-38-0	0.576	0.01		93	
	inorganic material	manganesedioxide	1313-13-9	0.658	0.01	0.02	106	263
pcb metal	non noble metal	copper	7440-50-8	21.446	0.35	0.35	3466	3466
pcb plastic	plastics	epoxy resin	-	105.646	1.71		17075	
	inorganic material	glass fibre wool	65997-17-3	129.123	2.09	3.80	20870	37945
pcb plating	noble metal	gold	7440-57-5	0.066			11	
	non noble metal	nickel	7440-02-0	3.029	0.05	0.05	490	501
dcb ceramic	inorganic material	alumina	1344-28-1	723.354	11.69	11.69	116913	116913
dcb metal	non noble metal	copper	7440-50-8	661.840	10.70	10.70	106971	106971
deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com